

Supplier Name: **Texas Instruments Inc. (DUNS# 00-732-1904)**
 Contact Info: ti.com/support
 Form/Declaration Type: **Distribute - RoHS and IEC 62474 DB**
 Created on: **05/31/2022**

Details for "LM2595S-ADJ"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM2595S-ADJ	SNPB	Level-3-235C-168 HR	Texas Instruments Electronics	KTT 5	10.2 x 9 x 4.5	1597

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.345226	99.993338	999933	0.021617	216
Copper and Its Alloys	Iron	7439-89-6	0.000003	0.000869	9	0	0
Nickel and Its Alloys	Nickel	7440-02-0	0.000005	0.001448	14	0	0
Other Inorganic Materials	Sulfur	7704-34-9	0.000001	0.00029	3	0	0
Other Nonferrous Metals and Alloys	Manganese	7439-96-5	0.000004	0.001159	12	0	0
Precious Metals	Silver	7440-22-4	0.00001	0.002896	29	0.000001	0
Sub-Total			0.345249	100	1000000	0.021618	216
Die Attach Adhesive							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	3.041909	95.500001	955000	0.190472	1905
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.063705	2.000003	20000	0.003989	40
Precious Metals	Silver	7440-22-4	0.079631	2.499996	25000	0.004986	50
Sub-Total			3.185245	100	1000000	0.199447	1994
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	794.947566	99.60004	996000	49.776421	497764
Copper and Its Alloys	Phosphorus	7723-14-0	0.079806	0.009999	100	0.004997	50
Other Nonferrous Metals and Alloys	Tin	7440-31-5	1.19709	0.149985	1500	0.074957	750
Precious Metals	Silver	7440-22-4	1.915344	0.239976	2400	0.119931	1199
Sub-Total			798.139806	100	1000000	49.976306	499763
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	1.029	15	150000	0.064432	644
Other Nonferrous Metals and Alloys	Tin	7440-31-5	5.831	85	850000	0.365114	3651
Sub-Total			6.86	100	1000000	0.429546	4295
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	697.866913	89	890000	43.697621	436976
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	23.523604	3	30000	1.472954	14730
Thermoplastics	Epoxy	85954-11-6	62.72961	8	80000	3.927876	39279
Sub-Total			784.120127	100	1000000	49.09845	490985
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.385976	100	1000000	0.274632	2746
Sub-Total			4.385976	100	1000000	0.274632	2746
Total			1597.036403			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSLs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 05/31/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J5709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.